

Lecture 4: Benefits of Scaling III

- Announcements:
- HW#1 online; due Friday next week
- We'll go 1.5 hours today; but I would like to go 1.5 hours all days starting next week until we make up the first week

- Today:
- Reading: Senturia, Chapter 1
- Lecture Topics:

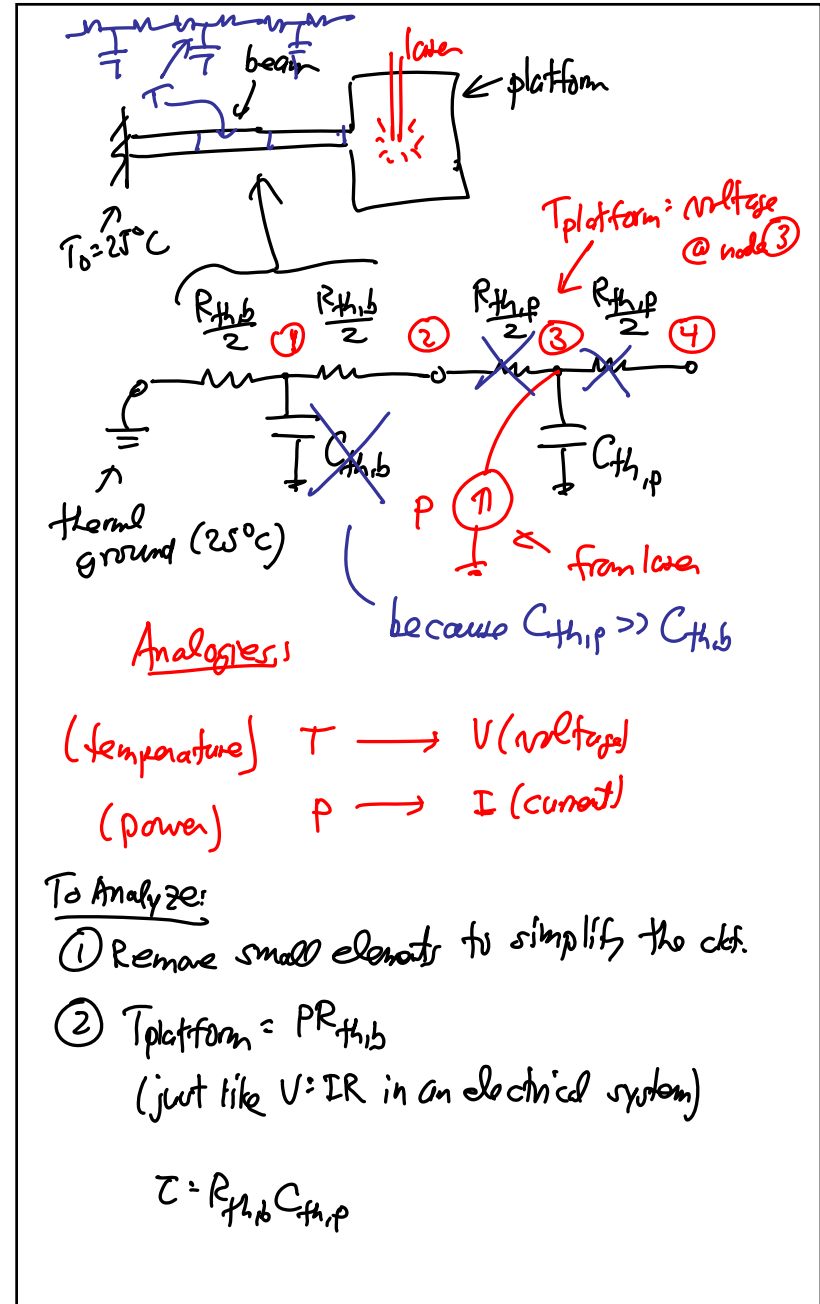
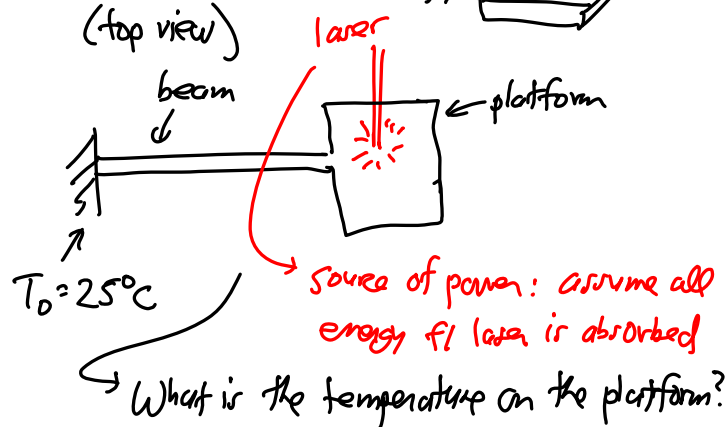
↳ Benefits of Miniaturization

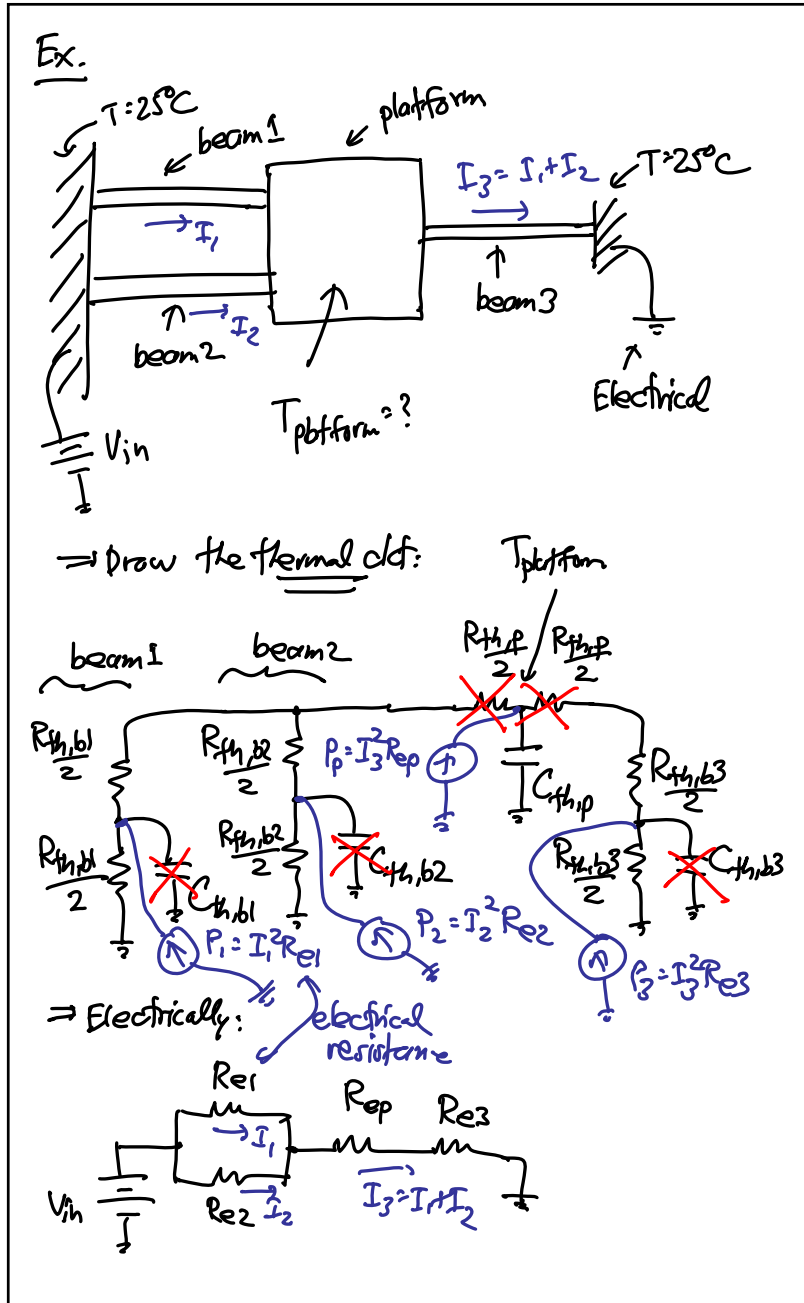
↳ Examples

- GHz micromechanical resonators
- Chip-scale atomic clock
- Thermal Circuits
- Micro gas chromatograph

- Last Time: Covering thermal circuit modeling ... which we now continue ...

Ex. MEMS type structure  
 (top view)





To Analyze:

- ① Electrical Analysis:  $I_3 = I_1 + I_2 = \frac{V_{\text{in}}}{R_{e,\text{tot}}}$
- ② Get power,  $P_i$ 's.  $= \frac{V_{\text{in}}}{R_{e1} || R_{e2} + R_{ep} + R_{e3}}$
- ③ Use superposition to solve the thermal ckt.  
 $\rightarrow$  handle one power source @ a time, then sum the temperatures (i.e., thermal voltages) to get the total temp. @ any node.

$$\left. \begin{array}{l} P_1 \rightarrow T_{\text{platform},1} \\ P_2 \rightarrow T_{\text{platform},2} \\ \vdots \\ P_3 \rightarrow T_{\text{platform},3} \end{array} \right\} T_{\text{platform}} = \sum_{i=1}^3 T_{\text{platform},i}$$

Use fn  $\tau$ .

$$\left\{ \begin{array}{l} C_{th,p} \\ R_{th,i1} || R_{th,i2} || R_{th,i3} \end{array} \right.$$

